



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-12-04
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MY59*AM01J81	A	SA1A	2013-12-04
Amount	UoM	Unit type	ST ECOPACK Grade	
31.259	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X1.0	12	No lead	
Comment	Package: VDFPN 8 3x3x1.0 PITCH 0.65 SAWN			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	<b>false</b>
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	<b>false</b>
Product(s) does not meet EU RoHS requirements and is not under exemptions	<b>false</b>
Product(s) is obsolete, no information is available	<b>false</b>
Product(s) is unknown, no information is available	<b>false</b>
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MYS9*AM01J81					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Inorganic Material	4.467	mg	Supplier	Silicon Die	Silicone	7440-21-3		4.375	mg	979405	139955
Silicon Die			mg	Supplier	Metallization	Aluminium	7429-90-5		0.015	mg	3358	480
Silicon Die			mg	Supplier	Metallization	Tungsten	7440-33-7		0.024	mg	5373	768
Silicon Die			mg	Supplier	Passivation	Silicon Nitride	68034-42-4		0.004	mg	895	128
Silicon Die			mg	Supplier	Passivation	Silicon Oxide	7631-86-9		0.035	mg	7835	1120
Silicon Die			mg	Supplier	Passivation	Gamma-butyrolactone	96-48-0		0.01	mg	2239	320
Silicon Die			mg	Supplier	Passivation	Polyhydroxyamide	55295-98-2		0.004	mg	895	128
Leadframe	Copper and its alloy	9.029	mg	Supplier	Alloy	Copper	7440-50-8		8.698	mg	963340	278247
Leadframe			mg	Supplier	Alloy	Iron	7439-89-6		0.204	mg	22594	6526
Leadframe			mg	Supplier	Alloy	Phosphorus	7723-14-0		0.002	mg	222	64
Leadframe			mg	Supplier	Alloy	Zinc	7440-66-6		0.011	mg	1218	352
Leadframe			mg	Supplier	Alloy	Nickel	7440-02-0		0.104	mg	11518	3327
Leadframe			mg	Supplier	Alloy	Palladium	7440-05-3		0.009	mg	997	288
Leadframe			mg	Supplier	Alloy	Gold	7440-57-5		0.001	mg	111	32
Die Attach	Other Organic Material	0.140	mg	Supplier	Glue	Silver	7440-22-4		0.113	mg	808876	3615
Die Attach			mg	Supplier	Glue	Carbocyclic Acrylates	proprietary		0.014	mg	100215	448
Die Attach			mg	Supplier	Glue	Bismaleimide resin	proprietary		0.004	mg	28633	128
Die Attach			mg	Supplier	Glue	2-preponic acid, 2-methyl	68586-19-6		0.004	mg	28633	128
Die Attach			mg	Supplier	Glue	Additive	proprietary		0.004	mg	28633	128
Die Attach			mg	Supplier	Glue	Dicumyl peroxide	80-43-3		0.0007	mg	5011	22
Bonding Wire	Other Inorganic Material	0.19	mg	Supplier	Bonding Wire	Au	7440-57-5		0.19	mg	1000000	6078
Encapsulation	Other Organic Material	17.433	mg	Supplier	Molding Compound	Silica Fused	60676-86-0		16.335	mg	936962	522553
Encapsulation			mg	Supplier	Molding Compound	Epoxy Resin	Proprietary		0.523	mg	29999	16731
Encapsulation			mg	Supplier	Molding Compound	Phenol Resin	Proprietary		0.523	mg	29999	16731
Encapsulation			mg	Supplier	Molding Compound	Carbon Black	1333-86-4		0.052	mg	2983	1663